



No residue™ flux IF 2005K

INTERFLUX®
ELECTRONICS N.V.



Technical data IF 2005K
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Page 1

No clean, halide free, No residue™ soldering flux

Description:

Interflux® IF 2005K is a low solids no-clean flux, especially designed for lead-free wave soldering.

IF 2005K can also be used for SnPb wave soldering or selective soldering, however in these cases, respectively IF 2005M and IF 2005C are the first choices.

The IF 2005K activation system has been designed to give optimal wetting on virtually all lead – free surface finishes ,including OSP.

The flux is absolutely halide free, making it a very safe, reliable flux, extremely suitable for high end electronics, as well as for all other branches of the electronics industry.

All flux components can evaporate during the soldering process.

With no rosin nor resin to create sticky residue, there is nothing left behind after wave soldering to foul test pins or prevent electrical contact.

The flux is classified as OR/L0 according to EN and IPC standards.



More information:

<i>Flux application</i>	2
<i>Pre heat settings</i>	2
<i>Wave contact</i>	2
<i>White residues and cleaning</i>	3
<i>Product handling</i>	3
<i>Test results</i>	3
<i>Packaging</i>	4

Key advantages:

- Absolutely halide free
- For lead-free **and** SnPb soldering
- No residue™ technology
- Suitable for spray, foam, drop jet and dip fluxing

Physical properties

Appearance	Clear colourless liquid
Solid content	2,5% ± 0,3
Density at 20°C	0,810 g/ml – 0,812 g/ml
Water content	3-4%
Acid number	18 – 22 mg KOH/g
Flash point T.O.C	15°C (59°F)



Application of the flux

1. Foam fluxing:

To ensure good foaming, the level of flux needs to be at least 2–3 cm over the porous flux stone. The use of an air knife is **i m p e r a t i v e**.

2. Spray fluxing:

It is advisable to use a double spray stroke during fluxing, whenever possible and to keep the flux pressure low. The nozzle traverse speed is set to a

value which ensures that every point on the boards is sprayed twice, once from two different sides. When this condition is met the result is a 50% overlap on the spray pattern. This will give the most uniform spray pattern coverage. Spray pattern coverage can be checked by passing a piece of cardboard through the spray

fluxer. Remove it before it reaches the preheat unit. Additionally the spray fluxer settings need to be checked by passing a glass plate or empty circuit board through the fluxer. Remove it from the machine before it reaches the preheat unit and check it on flux quantity. There may be no drops present. Drops are a sign of excessive

flux and are difficult to evaporate. Reduce the flux amount until defects typical for a too low flux amount like, webbing, flagging, shorts and icicles are observed. From this point increase the flux level again until the defects disappear.

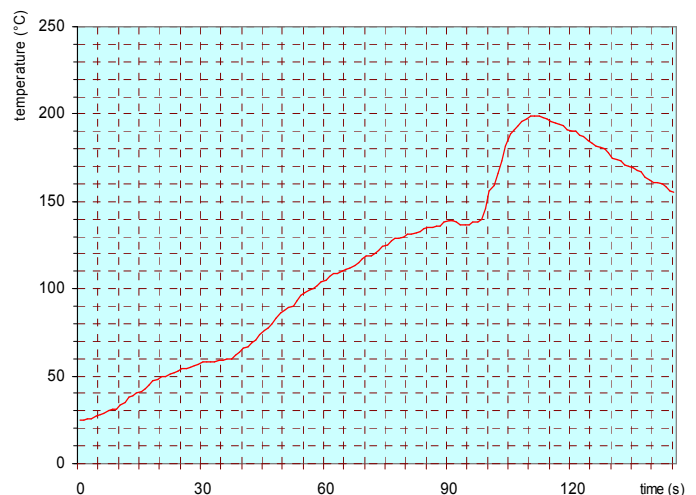
Preheating

The recommended preheat T° is: 100 - 160°C. This value is retrieved from field experience. The flux can have lower preheating T° as long as the solvent is evaporated before wave contact. Preheating T° above 150°C are to be

kept as short as possible in order to prevent flux exhaustion. If possible, avoid hot air preheating settings above 150°C. Always take into account the physical properties of the board, components and soldering application in order to

get an optimal final result .

Slope: 1-3°C/s



T° measured on the topside of the PCB on a lead-free soldering machine.

Wave contact

Typical wave contact or dwell time value is 3-4s when using a single solder wave. For double wave soldering systems the values will be 1-2s for the first wave and 2-4s for the second wave. Lower total dwell time limit is 2s.

Solder wetting can be optimal at low contact times however longer contact times are recommended to provide total flux wash off from the boards. The maximum upper limit will be determined by the level of shorts and physical limitations of

the board and components.



White residues and cleaning

White residues

If white residues appear after soldering there can be several reasons. In wave soldering with selective soldering carriers or selective soldering, the area of flux application is often larger

than the area with wave contact. This might result in white residues. Also too much flux application, or condensation of flux vapours might cause white residues. These residues are safe. The residues are

not sticky and won't cause contact problems. Less flux application, more heat or more wave contact can reduce these residues. IF 2005M gives less residues but has a smaller process window in activity.

Cleaning

The residues can be brushed away or evaporated with heat. The flux is cleanable with most conventional cleaning agents.

Handling

Storage

Store the flux in the original packaging, tightly sealed at a preferred temperature of +5° to +25°C.

IF 2005K density table, the right amount of thinner to be added can be calculated. T 2005M is the only thinner that can be used.

Reuse

Do not mix used and fresh flux.

Titration check

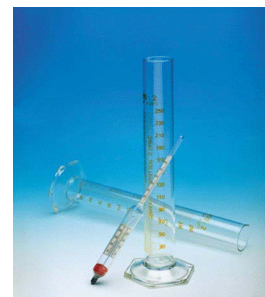
The solid content value of the IF 2005K flux shall be determined by using the Titration Kit for IF 2005K. Adjustments of the solid content may only be done by using T 2005M thinner.

Density control

The density of the IF 2005K flux shall be checked using the IF density meter, measuring density and flux temperature. With these values and the



Titration-Kit



Dichtemessgerät

Test results

conform EN 61190-1-2(2002) and IPC J-STD-004A

Property	Result	Method
Chemical		
qualitative copper mirror	pass	J-STD-004A IPC-TM-650 2.3.32
qualitative halide		
silver chromate (Cl, Br)	pass	J-STD-004A IPC-TM-650 2.3.33
activation class	OR L0	J-STD-004A
Environmental		
SIR test	pass	J-STD-004A IPC-TM-650 2.6.3.3



Packaging:

IF 2005K is available in the following packages:

- 10 litres polyethylene drums
- 25 litres polyethylene drums
- 200 litres polyethylene drums

D i s c l i m e r

Because we cannot anticipate or control the many different conditions under which this information and our products may be used, we do not guarantee the applicability or the accuracy of this information or the suitability of our products in any given situation. Users of our products should make their own test to determine the suitability of each such product for their particular purposes. The product discussed is sold without such warranty, either express or implied.

Product information in other European languages can be obtained at Interflux® Electronics NV, 9042 Gent. .

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